

GP 2811

**CERTIFICATE OF MAILING BY FIRST CLASS MAIL (37 CFR 1.8)**

Applicant(s): Jack H. Linn, et al.

Docket No.

87552.99R134/SE-906D

Serial No.

09/316,580

Filing Date

May 21, 1999

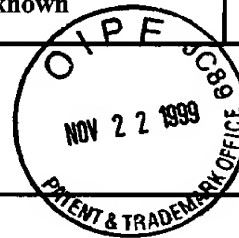
Examiner

Unknown

Group Art Unit

2811

Invention: BONDED WAFER WITH METAL SILICIDATION



I hereby certify that this IDS w/Form PTO-1449 (5 pgs)

(Identify type of correspondence)

is being deposited with the United States Postal Service as first class mail in an envelope addressed to: The

Assistant Commissioner for Patents, Washington, D.C. 20231 on

November 18, 1999

(Date)

Penny R. Turrell

(Typed or Printed Name of Person Mailing Correspondence)

  
(Signature of Person Mailing Correspondence)

Note: Each paper must have its own certificate of mailing.

RECEIVED

NOV 23 1999

TECHNOLOGY CENTER 2800